



SOT1156-1

plastic, thermal enhanced extremely thin small outline
package; no leads; 12 terminals

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2521-12
Package type industry code	DFN2521-12
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	17-9-2010

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.4	-	2.5	2.6	mm
E	package width		2	-	2.1	2.2	mm
A	seated height		[tbd]	-	[tbd]	0.5	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	12	-	



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2. Package outline

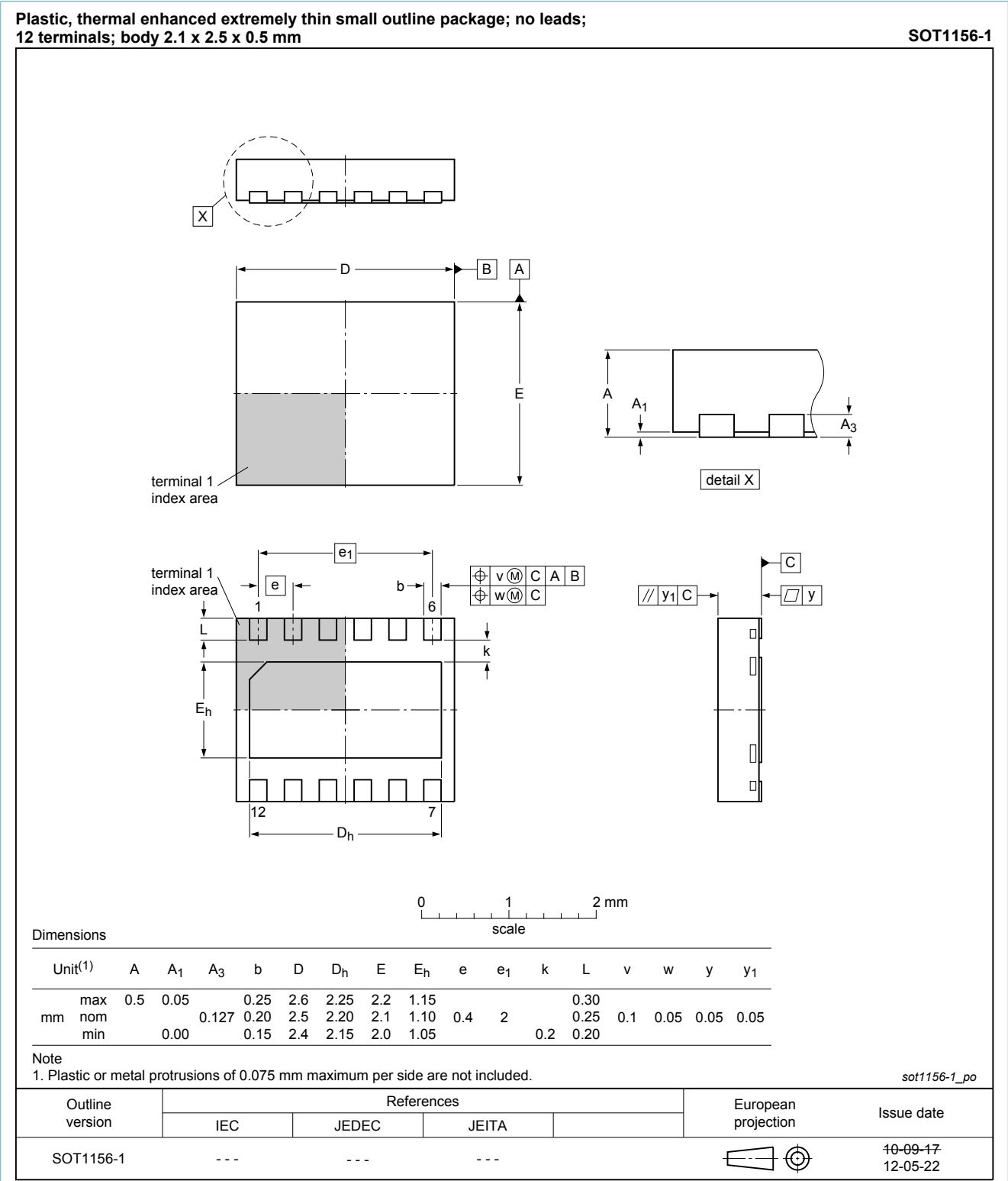


Fig. 1. Package outline DFN2521-12 (SOT1156-1)

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3. Soldering

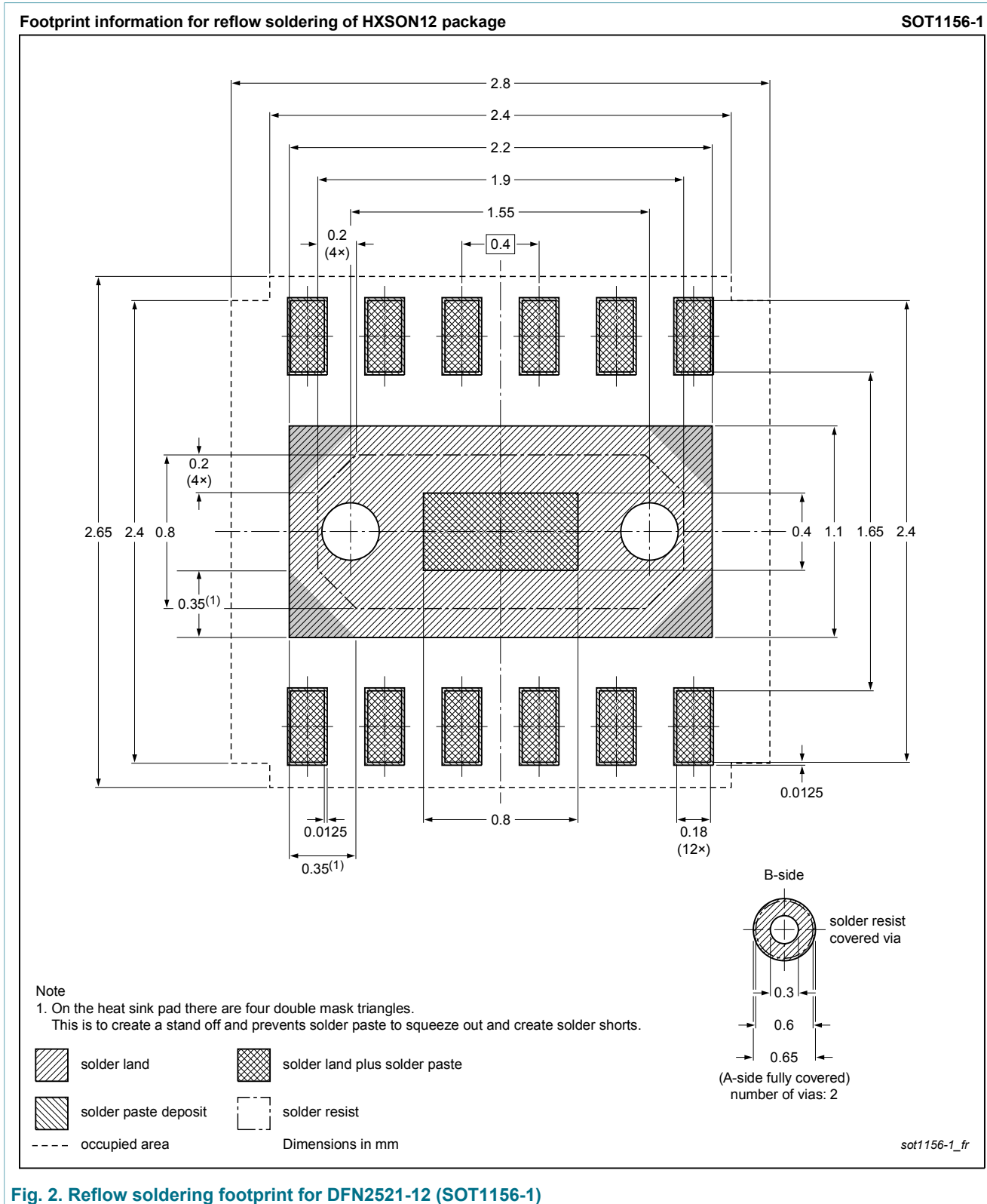


Fig. 2. Reflow soldering footprint for DFN2521-12 (SOT1156-1)

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4. Legal information

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Date of release: 8 February 2016